

ENGINEER	RING DEPT.	PRODUCT SPECIFICATION	SPEC.NO.:	SPCP008L
REVISIONS	ECN13008-0	For CP35 Series Power Connector	PAGE:	1/6

#### 1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire

#### 2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment

MIL - STD - 1344 Test methods for electrical connectors

J-STD-020 Resistance to soldering Temperature for through hole Mounted Devices SS-00254 Test methods for electronic components ,LEAD-FREE soldering Part design

standards

3. APPLICABLE SERIES NO.: CP35 Series

# 4. SHAPE, CONSTRUCTION AND DIMENSIONS See attached drawings

#### 5. MATERIALS

See attached drawings

#### 6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings



REVIEWED: <u>David</u> APPROVED: <u>Eisley</u> VERIFIED: <u>Steven</u>.



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# 7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT		TI	
7.1	Rated voltage(max.)		600V AC (r.m.s.)		s.)	
		Circuits/Wire gage	2	4-6	8-12	14-24
		AWG#20 wire gage	7.0A	5.5A	5.0A	4.5A
	Rated Current(max.)	AWG#22 wire gage	6.0A	4.5A	4.0A	3.5A
	and Applicable Wire	AWG#24 wire gage	5.5A	4.5A	3.5A	3.0A
	(Wire-to-Board)	AWG#26 wire gage	4.5A	4.0A	3.5A	2.5A
		AWG#28 wire gage	4.0A	3.0A	3.0A	2.0A
		AWG#30 wire gage	3.5A	3.0A	2.5A	1.0A
		Circuits/Wire gage	2	4-6	8-12	14-24
	Rated Current(max.) and Applicable Wire	AWG#20 wire gage	6.5A	5.0A	4.5A	4.0A
		AWG#22 wire gage	5.5A	4.0A	3.5A	3.0A
		AWG#24 wire gage	5.0A	4.0A	3.0A	2.0A
	(Wire-to-Wire)	AWG#26 wire gage	4.0A	3.0A	2.5A	1.5A
		AWG#28 wire gage	3.0A	2.0A	2.0A	1.0A
		AWG#30 wire gage	3.0A	2.0A	2.0A	1.0A
7.2	Contact resistance	Dry circuit of DC 20mV max., 100mA max., Wire resistance shell be removed from the measured value.	Less than $10 \text{ m}\Omega$			
7.3	Dielectric strength	When applied AC 1500 V 1 minute between adjacent terminal	No Breakdown			
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than $1000 \text{ M}\Omega$		1	
7.5	Contact resistance on Crimped portion	Crimp the wire to the terminal, measure by drucircuit, 20mV max., 100mA max., Wire resistance shall be removed from the measured value.	Less than 5 m $\Omega$			

# 8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Wire size	Specified wire size	Accepts AWG
			#20-#30



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	ITEM	TEST CONDITION	REQUIREMENT
8.2	Terminal crimp strength	When crimped AWG#20 size wire	More than 7.0 Kgf
		When crimped AWG#22 size wire	More than 5.0 Kgf
		When crimped AWG#24 size wire	More than 3.0 Kgf
		When crimped AWG#26 size wire	More than 2.0 Kgf
		When crimped AWG#28 size wire	More than 1.2 Kgf
		When crimped AWG#30 size wire	More than 0.8 Kgf
8.3	Terminal insertion force	Insertion speed 25± 3 mm per minute into housing	Less than 1.5 Kgf
8.4	Terminal retaining force in insulator	Retention speed 25± 3 mm per minute from Wire to Wire Housing	More than 3.0 Kgf
8.5	Single contact insertion force	Measure force to insertion using mating square pin at speed 25± 3 mm per minute	700 gram max.
8.6	Single contact withdrawal force	Measure force to withdrawal using mating square pin at speed 25± 3 mm per minute	150 gram min.
8.7	Pin retention force in Board mount Header	Push Pin for insulator base at speed 25± 3 mm per minute	More than 1.5 Kgf
8.8	Durability	Connector shall be subjected to 30 cycles of	Contact resistance:
		insertion and withdrawal	Less than twice of initial
8.9	Locking force	While with drawing plug&receptacle without terminal at speed 25± 3 mm per minute	More than 5.5 Kgf

#### 8.10 Insertion Force and Withdrawal Force:

### 8.10.1 Test method:

Housing with crimped contacts and a header shall be mated and unmated on the same axis. Initial insertion and withdrawal forces and withdrawal force at 30<sup>th</sup> shall be measured for single circuit and multi-circuits. For the measurement of single circuit, the housing lock shall be removed.



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# 8.10.2 Requirements:

6.10.2 Require	ments.	Unit: Kgf
NO. OF CIRCUITS	INSERTION FORCE Max.)	WITHDRAWAL FORCE (Min.)
2	2.0	0.5
4	3.0	1.0
6	6.0	1.5
8	7.0	2.0
10	9.0	2.5
12	10.0	3.0
14	11.0	3.5
16	12.0	4.0
18	13.0	4.5
20	14.0	5.0
22	15.0	5.5
24	16.0	6.0

## 9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.
9.2	Vibration	1.5 mm 10-55-10 HZ/minute each 2 hours for X, Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Heat aging	105± 2°C, 96 hours	No damage
9.4	Humidity	60± 2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.5	Temperature cycling	One cycle consists of: (1) -55 +0/-3 °C, 30 min. (2) Room temp. 10-15 min. (3) 105 +3/-0 °C, 30 min. (4) Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial



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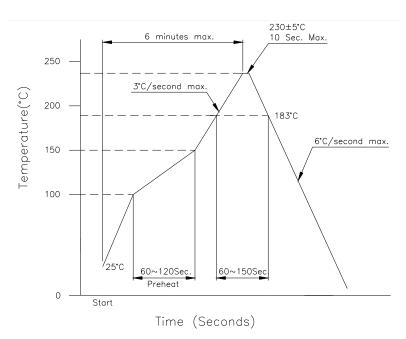
	ITEM	TEST CONDITION	REQUIREMENT
9.6	Salt spray	Temperature: 35± 3°C	Appearance: No damage
		Solution: 5± 1%	Contact resistance:
		Spray time: 48± 4 hours  Measurement must be taken after water rinse	Less than twice of initial
9.7	Solder ability	Tin-Lead Process:	Minimum:
		Soldering time: 5 ± 0.5 second	90% of immersed area
		Soldering pot: 230 ± 5°C	
		Lead-Free Process:	
		Soldering time: 3 ± 0.5 second	
		Soldering pot: 245 ± 5°C	
9.8	Resistance to soldering heat	DIP Type Tin-Lead Process:	No damage
		Soldering time: 5 ± 0.5 second	
		Soldering pot: 240 ± 5°C	
		<b>DIP Type Lead-Free Process</b>	
		Soldering time: 5 ± 0.5 second	
		Soldering pot: 260 ± 5°C	
		SMT Type Tin-Lead Process:	
		Refer Reflow temperature profile(11.1)	
		Soldering time: 10 second Max.	
		Soldering pot: 230 ± 5 °C	
		SMT Type Lead-Free Process:	
		Soldering time: 20 second Max.	
		Soldering pot: 250~260°C	
		Refer Reflow temperature profile(11.2)	

10. AMBIENT TEMPERATURE RANGE: -40 to + 105°C

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# 11. Recommended IR Reflow Temperature Profile:

# 11.1 Using Typical Solder Paste



# 11.2 Using Lead-Free Solder Paste

